

PG Series Gaskleen[®] Purifier Assemblies and Manifolds

Description

Pall's Gaskleen® PG purifier assemblies have been designed to handle process flow rates up to 1,000 slpm.

- An optional bypass manifold is available complete with isolation valves and backplate for easy mounting.
- Pall's purification materials are available in every standard configuration.
- All purifier assemblies contain an integral 316L stainless steel particle filter.
- 100% helium leak and pressure tested.
- No detectable metal contribution above background in HCI gas with HCLP material
- No detectable metal contribution above background in HBr gas with HBRP material

Specifications

Assembly Flow Rates

- PG550: 75 slpm
- PG2400: 500 slpm
- PG11000: 1,000 slpm



Particle Filter Options

- PG550/PG2400: 0.4 μm or 0.003 μm
- PG11000: 0.4 µm

Connections

- ¼ in or ½ in gasket seal (VCR¹ or compatible) male/male
- Inlet/outlet isolation valves (for PG11000)

Assembly Material

- Electropolished 316L SS
- <0.25 μm/<10 μin Ra internal surface finish



Operating Conditions

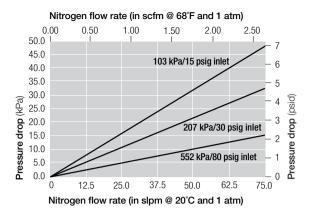
- Maximum operating pressure PG550/PG2400: 3.45 MPa/500 psig PG11000: 1.72 MPa/250 psig
- Maximum operating temperature: 100°C/212°F (INP, SIP, FCP, SF6P), 40°C/104°F (GEH4P, OXP, QLXP, HCLP, HBRP, CDAP)
- EU Pressure Equipment Directive: Assemblies have been evaluated for compliance with the European Union's Pressure Equipment Directive 2014/68/EU and are CE-marked.

¹ VCR is a trademark of Swagelok Co.

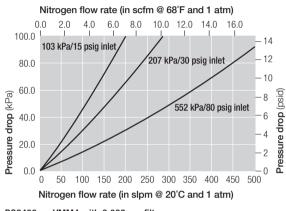
List of Purifiable Gases

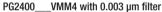
Gas Family	Material	Effluent Specification ²
Nitrogen, argon, helium, xenon, krypton, neon	INP	<1 ppb H_2O , O_2 , CO_2 and CO
Silane, hydrogen, methane, cyclopropane, propane, dimethyl ether	SIP	<1 ppb H_2O , O_2 , CO_2 and CO
Carbon monoxide	SIP	<1 ppb H_2O , O_2 , CO_2 , Ni(CO) ₄ , and Fe(CO) ₅
Fluoromethane, difluoromethane, trifluorine, tetrafluoroethane, pentafluoroethane, heptafluoropropane, carbon tetrafluoride, perfluoropropane, perfluorocyclobutane, hexafluoroethane	FCP	<1 ppb H_2O , O_2 , CO_2 and CO
Germane	GEH4P	<1 ppb H_2O , O_2 , CO_2 and CO
Sulfur hexafluoride	SF6P	<1 ppb H_2O , O_2 , CO_2 and CO
Air, carbon dioxide, oxygen, nitrous oxide	OXP	<10 ppb H ₂ O
Boron trichloride, chlorine, trichlorosilane, dichlorosilane	CLXP	<100 ppb H ₂ O
Hydrogen chloride	HCLP	<15 ppb H ₂ O
Hydrogen bromide	HBRP	< 50 ppb H ₂ O
Photolithography clean dry air	CDAP	 < 1 ppb H₂O, < 300 ppt organics (as C₄), < 10 ppt acid gases (as SO₂), < 15 ppt basic gases (as NH₃), < 1 ppt refractory compounds (as HMDSO)

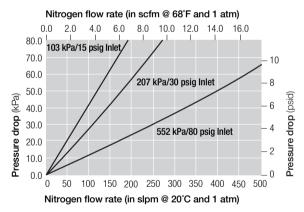
Pressure Drop vs. Gas Flow Rate



PG550 with 0.003 µm filter





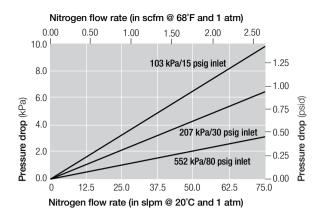


PG2400___VMM8 with 0.003 µm filter

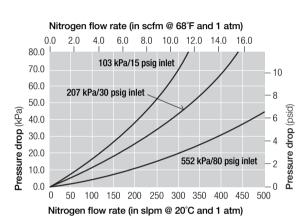
Nitrogen flow rate (in scfm @ 68°F and 1 atm) 0.0 10.0 15.0 20.0 25.0 30.0 35.0 5.0 80.0 70.0 10 103 kPa/15 psig Inlet 60.0 8 50.0 207 kPa/30 psig Inlet ହ ଧୁ 40.0

 ³
 ^{40.0}
 ³⁰
 ²⁰⁷
 ²⁰⁷
 ²⁰⁷
 ²⁰⁷
 ²⁰⁷
 ²⁰⁷
 ³⁰⁰
 ³⁰⁰
 ¹⁰⁰
 ²⁰⁰
 ³⁰⁰
 ⁴⁰⁰
 ⁵⁵²
 ^{kPa/30}
 ^{kPa/30}
 ^{bsig}
 ^{inter-6}
 ⁶
 ⁶
 ²⁰
 ⁰
 ¹⁰⁰
 ²⁰⁰
 ³⁰⁰
 ⁴⁰⁰
 ⁵⁰⁰
 ⁶⁰⁰
 ⁷⁰⁰
 ⁸⁰⁰
 ⁹⁰⁰
 ¹⁰⁰⁰
 ¹⁰⁰
 ²⁰⁰
 ^{20°}
 ^c
 ^{add}
 ^{ad}

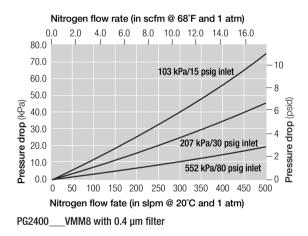
PG11000 Series assembly



PG550 with 0.4 µm filter

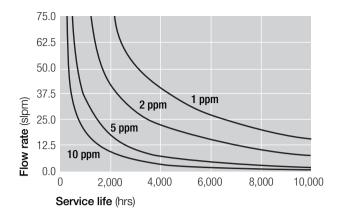


PG2400 VMM4 with 0.4 µm filter



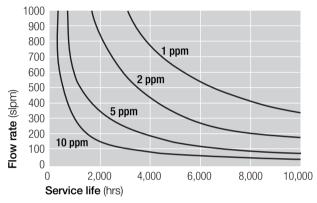
Note: For pressure drop information for a specific application, please contact Pall Microelectronics.

Lifetime Calculations



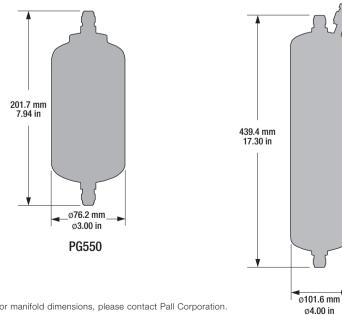
Pall AresKleen[™] purification material: inert gas service Gaskleen® PG550 purifier assembly, part # GLP9INPVMM4

Inlet pressure: 207 kPa (30 psig) contaminant challenge as H₂O

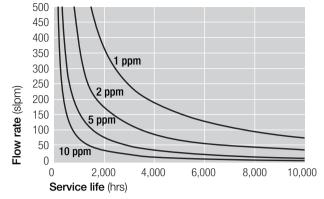


Pall AresKleen™ purification material: inert gas service Gaskleen® PG11000 purifier assembly, part # GLP110INPVFM8 Inlet pressure: 207 kPa (30 psig) contaminant challenge as H₂O

Nominal Assembly Dimensions



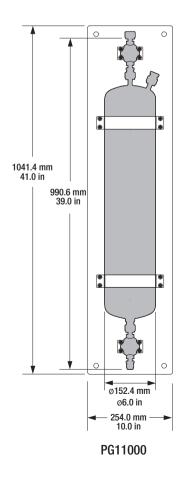
PG2400



Pall AresKleen[™] purification material: inert gas service Gaskleen® PG2400 purifier assembly, part # GLP24INPVMM4/VMM8

Inlet pressure: 207 kPa (30 psig) contaminant challenge as H₂O

Note: For lifetime calculations in a specific application, please contact Pall Microelectronics.



Technical Information

Impurity Removal as Tested in Specific Gases

Specific Gas	Impurity Removal Efficiency	
Inert gases: nitrogen, argon, helium, xenon, krypton, neon	<1 ppb H_2O , CO_2 , O_2 , and CO , as tested in argon and nitrogen using APIMS analyzer	
Flammable gases: silane, hydrogen, methane, ethane, cyclopropane, propane, dimethyl ether	<1 ppb H ₂ O, CO ₂ , O ₂ , and CO, as tested in argon, nitrogen and hydrogen using APIMS analyzer <1 ppb H ₂ O, as tested in carbon monoxide using trace moisture analyzer H ₂ O and siloxanes removed to trace levels, as tested in silane using APIMS	
Carbon monoxide	<1 ppb Ni(CO) ₄ , and < 1 ppb Fe(CO) ₅ , as tested in carbon monoxide using GC-ECD analyzer	
Fluorocarbons: fluoromethane, difluoromethane, trifluoromethane, tetrafluoroethane, pentafluoroethane, heptafluoropropane, carbon tetrafluoride, perfluoropropane, perfluorocyclobutane, hexafluoroethane	<1 ppb H ₂ O, CO ₂ , O ₂ , and CO, as tested in argon and nitrogen using APIMS analyzer <1 ppb O ₂ , as tested in trifluoromethane using trace oxygen analyzer <10 ppb H ₂ O, as tested in trifluoromethane using trace moisture analyzer and FTIR	
Germane	<1 ppb H_2O , CO_2 , O_2 , and CO , as tested in argon and nitrogen using APIMS analyzer	
Sulfur hexafluoride	<1 ppb H_2O , CO_2 , and O_2 , as tested in argon using APIMS	
Oxygenated gases: carbon dioxide, oxygen, nitrous oxide, clean dry air	<10 ppb H_2O <1 ppb H_2O , and CO_2 , as tested in argon using APIMS analyzer	
Chlorinated gases: boron trichloride, chlorine, trichlorosilane, dichlorosilane	<100 ppb H_2O <1 ppb H_2O , and CO_2 , as tested in argon using APIMS analyzer	
Halogenated gases: hydrogen chloride, hydrogen bromide	< 15 ppb H_2O as tested in hydrogen chloride using CRDS < 50 ppb H_2O as tested in hydrogen bromide using CRDS < 1 ppb H_2O as tested in argon using APIMS analyzer	
Photolithography clean dry air	< 1 ppb H_2O as tested in argon using APIMS analyzer < 300 ppt C_4H_8 as tested in argon using APIMS Analyzer < 10 ppt SO ₂ as tested in nitrogen using ion chromatograph < 15 ppt NH ₃ as tested in nitrogen using ion chromatograph < 1 ppt HMDSO as tested in argon using APIMS analyzer and baseline subtraction	

Unit conversion: 1 bar = 100 kilopascals

Part Numbers / Ordering Information

Series	Part Number ³	Description	
PG550	GLP9xxxxFVMM4	Purifier assembly, 75 slpm, 0.003 µm filter, ¼ in gasket seal (VCR or compatible) male/male	
	GLP9xxxxFMAN	Bypass manifold with GLP9xxxFVMM4 assembly	
	GLP9xxxxFVMM4GCMAN	Gas cabinet manifold with GLP9xxxFVMM4 assembly	
	GLP9xxxxVMM4	Purifier assembly, 75 slpm, 0.4 µm filter, ¼ in gasket seal (VCR or compatible) male/male	
	GLP9xxxxMAN	Bypass manifold with GLP9xxxVMM4 assembly	
	GLP9xxxxVMM4GCMAN	Gas cabinet manifold with GLP9xxxVMM4 assembly	
GLP24xxxxFVMM GLP24xxxxFMAN GLP24xxxxVMM4	GLP24xxxxFVMM4	Purifier assembly, 300 slpm, 0.003 µm filter, ¼ in gasket seal (VCR or compatible) male/male	
	GLP24xxxxFVMM8	Purifier assembly, 300 slpm, 0.003 µm filter, ½ in gasket seal (VCR or compatible) male/male	
	GLP24xxxxFMAN	Bypass manifold with GLP24xxxxFVMM8 assembly	
	GLP24xxxxVMM4	Purifier assembly, 500 slpm, 0.4 µm filter, ¼ in gasket seal (VCR or compatible) male/male	
	GLP24xxxxVMM8	Purifier assembly, 500 slpm, 0.4 µm filter, ½ in gasket seal (VCR or compatible) male/male	
	GLP24xxxxMAN	Bypass manifold with GLP24xxxxVMM8 assembly	
PG11000	GLP110xxxxVFM84	Purifier assembly, 1,000 slpm, 0.4 μ m filter, ½ in gasket seal (VCR or compatible) female inlet/male outlet	
	GLP110xxxxMAN ⁴	Bypass manifold with GLP110xxxVMM8 assembly	

 3 See list of purifiable gases on page 1. Example: GLP9INPFVMM4.

⁴ The PG11000 stainless steel assembly (used with all GLP110 part numbers) is fabricated in accordance with the ASME BPVC Section VIII, Division 1, and has a U-stamp. If the user determines that an L-stamp is required for a lethal service application, please contact Pall Microelectronics for cost and availability.



Microelectronics

25 Harbor Park Drive Port Washington, New York 11050 USA

+1.800.360.7255 toll free (toll free in USA only) +1.516.484.3600 phone +1.516.625.3610 fax microelectronics@pall.com

Visit us on the Web at www.pall.com/micro

Pall Corporation has offices and plants throughout the world. For Pall representatives in your area, please go to www.pall.com/contact.asp

Because of technological developments related to the products, systems, and/or services described herein, the data and procedures are subject to change without notice. Please consult your Pall representative or visit www.pall.com to verify that this information remains valid. Products in this document may be covered by the following patent number: US 7,465,692

© Copyright 2007, 2011, 2018 Pall Corporation. Pall, (PALL), and Gaskleen are trademarks of Pall Corporation. ® Indicates a Pall trademark registered in the USA. *Filtration. Separation. Solution.sm* is a service mark of Pall Corporation.